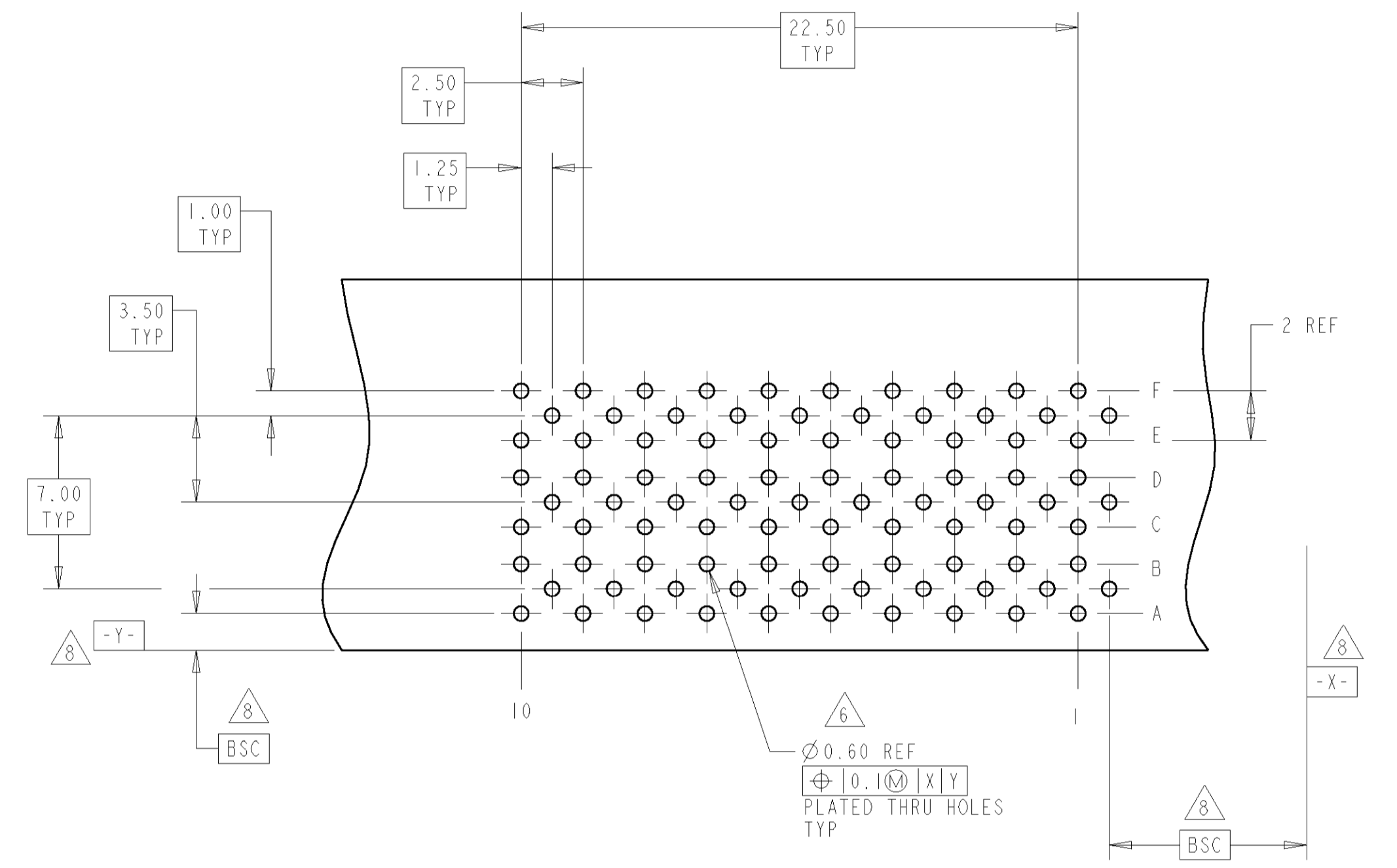
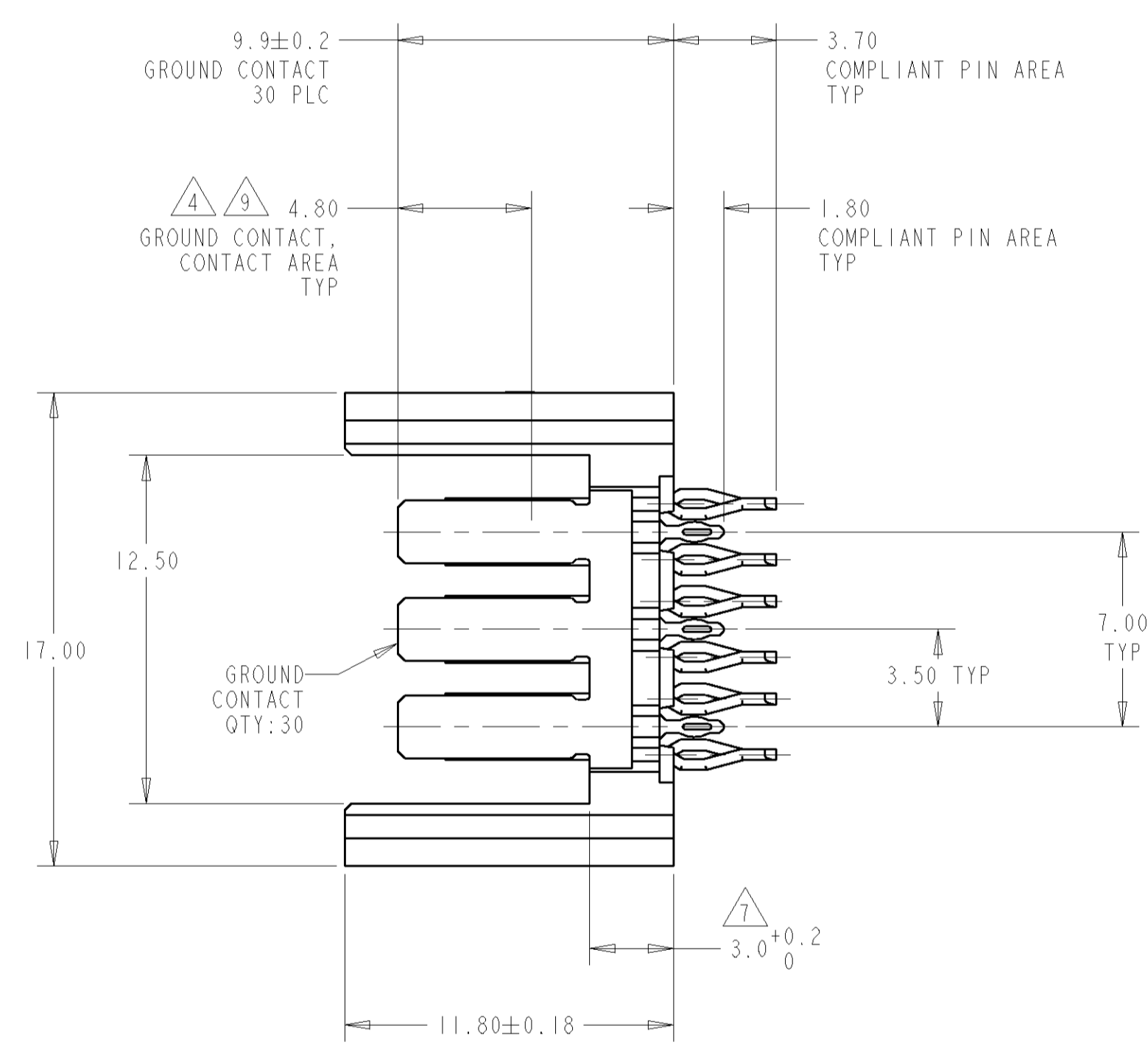
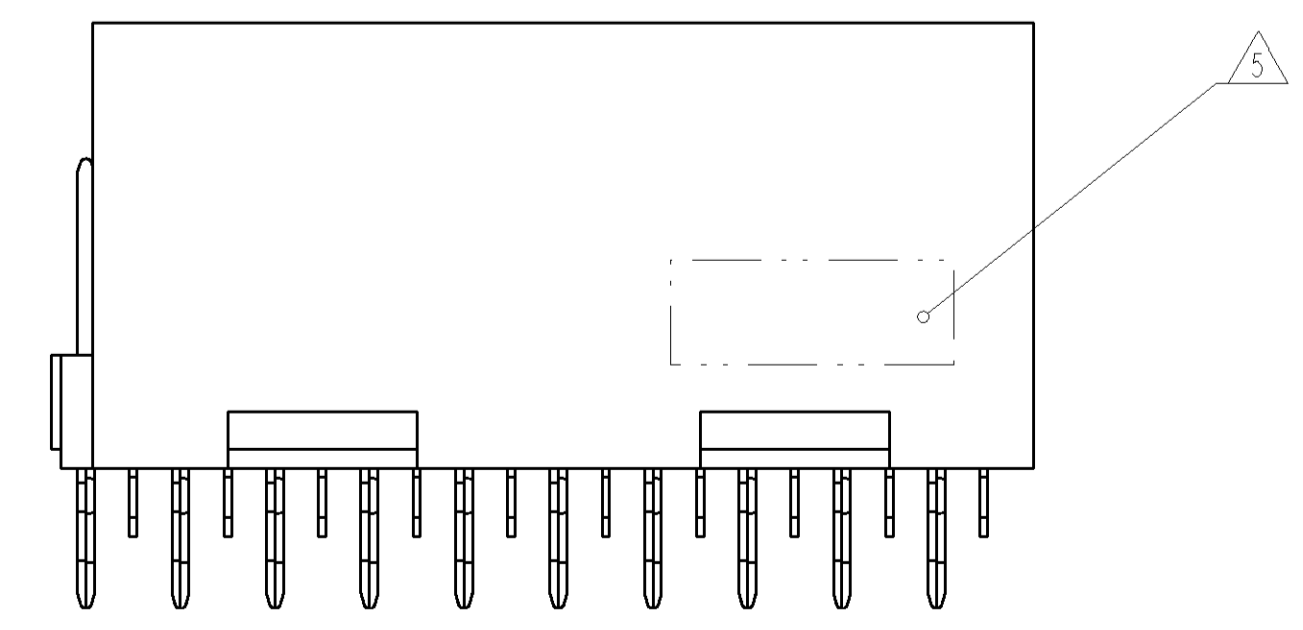
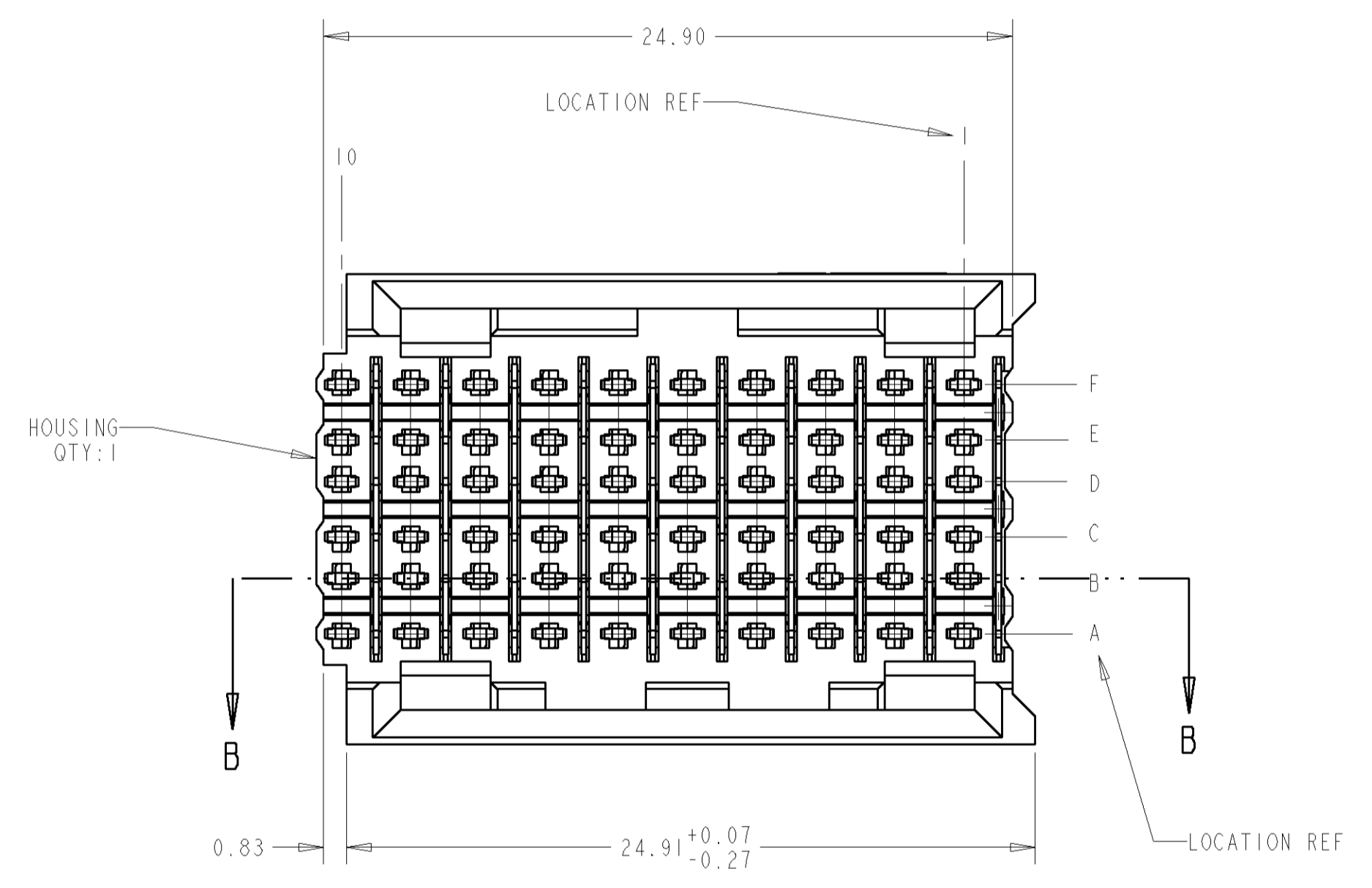
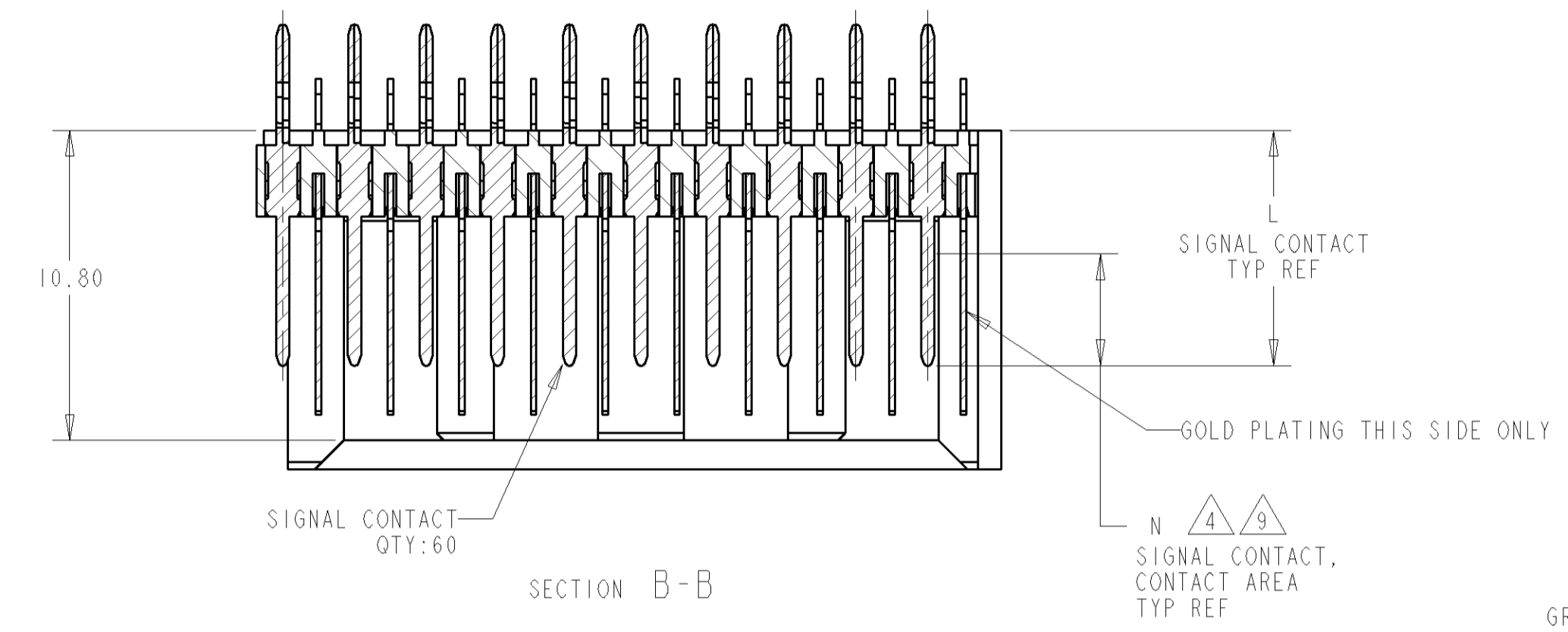


LOC	DIST	REV	DATE	BY	APPD
AD	47	G1	18JAN2007	JRP	RAP

- 2 PHOSPHOR BRONZE
- 3 LCP, UL94V-0
- 4 0.76µm MIN GOLD OVER 1.27µm MIN NICKEL UNDERPLATE OR GOLD FLASH OVER 0.76µm MIN PALLADIUM-NICKEL OVER 1.27µm MIN NICKEL UNDERPLATE ON CONTACT AREA. 0.76µm MIN TIN LEAD OVER 1.27µm MIN NICKEL ON COMPLIANT PIN AREA
- 5 CONNECTOR MARKED WITH PART NUMBER AND DATE CODE
- 6 REFERENCE APPLICATION SPEC 114-13020 FOR RECOMMENDED PLATED THRU HOLE DIAMETER AND PLATING THICKNESSES
- 7 APPLICATION SEATING HEIGHT TO PRINTED CIRCUIT BOARD
- 8 DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
- 9 CONTACT AREA LUBRICATED WITH BELLCORE APPROVED LUBRICANT TECHNICAL REFERENCE: GR-1217-CORE, ISSUE 1, NOVEMBER 1995



RECOMMENDED  
 PRINTED CIRCUIT BOARD  
 LAYOUT  
 COMPONENT SIDE OF PRINTED CIRCUIT BOARD

5.30	9.7	120674-2
3.90	8.2	120674-1
M	L	PART NUMBER

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		MATERIAL:		FINISH:		CUSTOMER DRAWING	
mm		0 PLC	±	HOUSING:	3	SIGNAL CONTACT:	4	SCALE	5:1
		1 PLC	±					SHEET	1
		2 PLC	±0.13					OF	1
		3 PLC	±0.05					REV	G1
		4 PLC	±						
		ANGLES	±						

APVD	H. MOLL	5-19-99		Tyco Electronics Harrisburg, PA 17105-3608
CHK	H. ANDREWS	5-19-99		
NAME	HEADER ASSEMBLY, 60 POSITION, 6 ROW, BACKPLANE CONNECTOR, Z-PACK HS3			
PRODUCT SPEC				
APPLICATION SPEC				
SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO	
A1	00779	C=120674		